

List of cards (samples are shown in red frame)

- A1 Infrared sensor, imager
- A2 Infrared sensor
- A3 2 axis galvano optical scanner
- A4 DMD (Digital Micromirror Device)
- A5 Digital cinema DMD
- A6 Optical encoder
- A7 Piezoelectric, thermal inkjet printer head
- A8 Electrostatic inkjet printer head
- A9 MEMS resonator
- A10 MEMS resonator (disk, Lamb etc.)
- A11 FBAR (Film Bulk Acoustic Resonator)
- A12 SAW device on LSI
- A13 Tunable SAW filter using variable capacitor
- A14 SAW passive wireless sensor

- B1 Piezoresistive pressure sensor
- B2 Integrated capacitive pressure sensor
- B3 Resonant pressure sensor
- B4 Capacitive vacuum sensor
- B5 Capacitive vacuum sensor products
- B6 MEMS microphone
- B7 MEMS microphone wafer
- B8 MEMS microphone for humid environment
- B9 Capacitive accelerometer for automobile
- B10 Wafer of accelerometer by surface micromachining
- B11 Various accelerometers
- B12 Integrated capacitive accelerometer
- B13 3-axis accelerometer
- B14 Electrostatically levitated rotational gyroscope

- C1 Electromagnetically driven resonating gyroscope
- C2 Silicon ring gyroscope
- C3 Piezoelectric gyroscope
- C4 Electrostatically driven capacitive sensing gyroscope
- C5 Yaw rate, acceleration sensor
- C6 Accelerometer and gyroscope for automobile and smartphone
- C7 Patterning
- C8 Etching (Deep RIE, XeF₂ Etching, etc)

- C9 Deposition
- C10 Probe for scanning probe microscope (SPM)
- C11 Near-field optical probe and bow-tie antenna
- C12 Highly sensitive sensors using thin resonator
- C13 Multi-probe data storage
- C14 Electron source

- D1 Electrode for biopotential recording
- D2 Semiconductor ion sensor (ISFET)
- D3 Catheter pH, CO₂ sensor
- D4 Intermittent sampling continuous blood gas monitor
- D5 Application of ISFET to dentistry, oceanography and fish cultivation
- D6 Micro ISFET and integrated micro probe
- D7 Gas sensors
- D8 Disposable chemical analysis chip
- D9 Bio LSI and tactile sensor network
- D10 Catheter blood pressure sensor
- D11 Active catheter
- D12 Multi-link motion mechanism using shape memory alloy
- D13 Imaging for minimal invasive medicine
- D14 Implantable stimulator

- E1 LIGA process
- E2 Laser processes and stealth dicing
- E3 Anodic bonding
- E4 Anodically bondable LTCC with electrical feedthrough
- E5 Bonding materials
- E6 Shared CMOS LSI wafer
- E7 Laser-erased wafer process
- E8 Massive parallel electron beam write
- E9 Micro pump, micro valve and chemical analysis system for liquid
- E10 Micro mixer and particle analysis
- E11 Flow sensor and mass-flow controller for gas
- E12 Bakable micro valve and anticorrosive mass-flow controller
- E13 Sensing in harsh environment
- E14 Silicon carbide (SiC) mold for glass press-molding

- F1 Small size gas turbine engine dynamo
- F2 Si micro-turbine and thermoelectric generator
- F3 SiC and PZT by lost-mold process, Si₃N₄ by reaction sintering
- F4 Micro fuel cell
- F5 Micro fuel reformer
- F6 Digital micro thruster (solid rocket engine array)
- F7 Electrostatic micro motor, actuator
- F8 Distributed electrostatic micro actuator
- F9 Piezoelectric micro stage
- F10 Lateral motion piezoelectric microactuator
- F11 Tactile display and tactile imager
- F12 Micro refrigeration system
- F13 Thermal MEMS switch
- F14 Electrostatic and piezoelectric MEMS switch

- G1 Wavelength swept pulsed quantum cascade laser
- G2 Optical melt pressure & temperature sensor
- G3 Capacitive high sensitive differential pressure sensor "MANOSTAR"
- G4 10th anniversary of SEMI MEMS seminar

- H1 Tohoku Univ. and Belgium IME
- H2 Poly-SiGe for MEMS sensor applications
- H3 MEMS gyroscope on CMOSIC using poly-SiGe
- H4 SiGe micro-mirror array on CMOS IC
- H5 CMORE SiGeMEMS multi project wafer
- H6 Holographic displays
- H7 MEMS for energy harvester & electronic noise

- I1 Piezoelectric and electrostatic optical scanners
- I2 Immunological analyzer of *Helicobacter pylori*'s urease

- J1 Telegraph using electric wire in bottom of ocean
- J2 CPU board for super computer
- J3 Microwave radar using anode split magnetron
- J4 Shimada laboratory in which high power anode split magnetron was developed before the end of war (Z project)
- J5 Crystal detector and point contact transistor
- J6 Transitions of power devices used in Shinkansen
- J7 Massive parallel electron beam write
- J8 Electromagnetically levitated lamp
- J9 Model railway of magnetically levitated linear liner
- J10 Linear Chuo Shinkansen using superconductivity and its model railway
- J11 Linear subway (Linear metro) travelling on wheels
- J12 Micro car
- J13 Disassembly of FOMA (3G) smartphone
- J14 Continuous arterial pressure waveform with Tonometry
- J15 Topics related to collected books
- J16 Micro flying robot (μ FR)
- J17 Planimeter (area meter) and proportional compass

- K1 Books, photograph and other materials about Prof. Jun-ichi Nishizawa

- L1 Hermetic seal bonding at low temperature with sub-micron Au particles

- M1 **Five-storied pagoda made of glass**

- N1 Infrared array sensor (Panasonic Corp.)
- N2 3D LSI (Honda research Institute Japan, Co Ltd)
- N3 Remote control switch using energy harvester (EnOcean GmpH)
- N4 Membrane switch array for electrophoresis display and oscillometric blood pressure monitor (E-paper, Tokyo Sanyo Electric Co. Ltd, Kazuo Senda)